



Product Change Notice

Micron PCN: 31020
 Date: 10/22/2013

Type of Change:	End of Life	
Title of Change:	Specific NAND Flash Part Number Terminations	
Description of Change:	Multiple NAND Flash Part Numbers are being terminated to enable improved supply line efficiency and focus on Microns' commitment to NAND technology. Production volumes for the impacted Part Numbers are zero or do not justify the continued availability.	
Reason for Change:	Optimization of Manufacturing Efficiency	
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Product Affected: NAND Flash

Affected Part Number	Replacement Part Number	Key Difference
NAND128W3A0BN6E	NAND128W3A0BN6F	Packing change from Try to Tape & Reel
NAND128W3AABN6E	NAND128W3AABN6F	Packing change from Try to Tape & Reel
NAND256W3A0BE06	None	Contact Micron representative
NAND256W3A0BN6E	NAND256W3A0BN6F	Packing change from Try to Tape & Reel
NAND256W3A0BZA6E	NAND256W3A2BZA6E	Chip Enables from CE care to CE don't care
NAND256W3A2BE06	None	Contact Micron representative
NAND512R3A2SE06	None	Contact Micron representative
NAND512R3A2SN6E	None	Contact Micron representative
NAND512R3A2SN6F	None	Contact Micron representative
NAND512R3A2SZA6F	NAND512R3A2SZA6E	Change packing from Tape and Reel to Try
NAND512W3A2SE06	None	Contact Micron representative
MT29F1G08ABADAH4-E:D	MT29F1G08ABADAH4-ITE:D	Temperature range from Commercial to Industrial
MT29F1G08ABADAWP-ITE:D	MT29F1G08ABADAWP-IT:D	On-Die ECC must be enabled by user
MT29F1G08ABBD4H4-ITE:D	MT29F1G08ABBD4H4-IT:D	NAND Line Item reduction update
MT29F1G16ABBD4HC:D	MT29F1G16ABBD4HC-IT:D	Temperature range from commercial to industrial
MT29F1G16ABBDAM68A3WC1	MT29F1G16ABBEAM68M3WC1	On-Die ECC not supported
MT29F2G08ABAEAH4-ITE:E	MT29F2G08ABAEAH4-IT:E	NAND Line Item reduction update
MT29F16G08AJADAWP:D	MT29F16G08AJADAWP-IT:D	Temperature range from commercial to industrial
MT29F4G08ABADAH4-E:D	MT29F4G08ABADAH4-ITE:D	Temperature range from commercial to industrial
MT29F4G08ABBD4H4-ITE:D	MT29F4G08ABBD4H4-IT:D	NAND Line Item reduction update
MT29F4G16ABADAM60A3WC1	MT29F4G16ABAEAM70M3WC1	Litho change from 34nm to 25nm

Note: Per JEDEC Standard JESD46-C Section 3.2.3; lack of acknowledgment of this PCN within 30 days constitutes acceptance of change



Affected Part Number	Replacement Part Number	Key Difference
MT29F8G08ADADAH4:D	MT29F8G08ADADAH4-IT:D	Temperature range from commercial to industrial
MT29F8G16ADBDAH4:D	MT29F8G16ADBDAH4-IT:D	Temperature range from commercial to industrial
MT29F16G08AFABAWP:B	MT29F16G08ABACAWP-Z:C	Litho change from 34nm to 25nm
MT29F16G08AFABAWP-IT:B	MT29F16G08ABACAWP-ITZ:C	Litho change from 34nm to 25nm
MT29F8G08ABCBBH1-12:B	MT29F8G08ABACAH4:C	From BGA100 to BGA63 package
MT29F8G08ABCBBH1-12IT:B	MT29F8G08ABACAH4-IT:C	From BGA100 to BGA63 package

Method of Identification:

By Part Numbers

Micron Sites Affected: All Sites

Last Buy Date: 22-Apr-2014

Last Ship Date: 22-Oct-2014

Orders placed prior to the LTB date are subject to current inventory levels, which may vary based on market conditions and customer demand. Early orders are encouraged.